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NEWS RELEASE

Mitsui Kinzoku Plans to Increase MicroThin™ Production Capacity

— Increasing Production Capacity 700,000 m^2 to 5.6 Million m^2 per Month by 2030 —

Mitsui Mining and Smelting Co., Ltd. (NOU Takeshi, President; hereinafter "Mitsui Kinzoku") has a plan to gradually increase the MicroThin™ production capacity of the Ageo Operation (Ageo City, Saitama) and Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn Bhd) after 2025. Production will increase 300,000 m^2 by fiscal 2027 and another 400,000 m^2 by 2030, bringing the total monthly production capacity to 5.6 million m^2.

Mitsui Kinzoku's MicroThin™ product is an extremely-thin electrodeposited copper foil with carrier that has a thickness of 1.5 to 5 μm suitable for the formation of fine circuits and multiple types of fine-roughening treatment. It is mainly used for semiconductor package PCBs and motherboards for smartphones (HDI printed circuit boards).

Demand of semiconductor package PCBs is growing for memories for data center and automobile and it will continue to increase for new applications such as multilayer PCBs for optical modules and ultra-high speed infrastructure and flexible PCBs for ultra-high speed communication devices.

We are planning to increase the monthly production capacity from 4.9 million m^2 to 5.6 million m^2 by implementing DX using big data and data science in the manufacturing processes to improve productivity, and by enhancing the equipment used in processing, inspection and other processes.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing its vision for 2030, "Building new businesses —and the future— with our material intelligence," based on its purpose, "We promote the well-being of the world through a spirit of exploration and diverse technologies."

■ MicroThin™ production capacity (for reference, m^2 per month)

	2024	2027	2030
Ageo Operation	2.5 million	2.6 million	2.8 million
Malaysia Plant	2.4 million	2.6 million	2.8 million
Total	4.9 million	5.2 million	5.6 million

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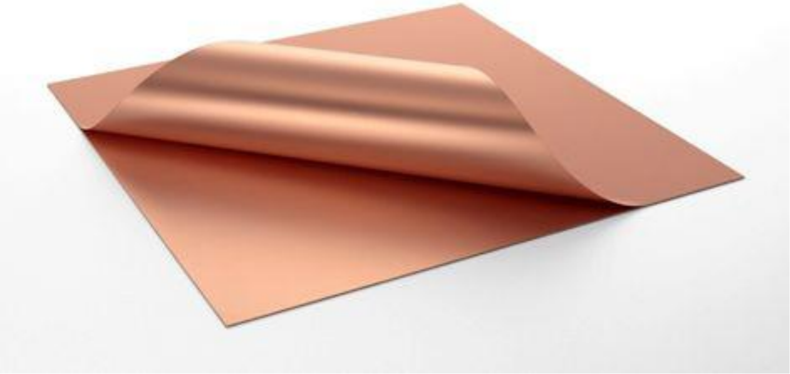
Picture of MicroThin^{TM}



Top: Copper carrier foil (thickness: 18µm or 12µm)
Bottom: Extremely-thin copper foil (thickness: 1.5µm to 5µm)